

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c64a-20i-pt

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

1.0 GENERAL DESCRIPTION

The PIC16CXX is a family of low-cost, high-performance, CMOS, fully-static, 8-bit microcontrollers.

All PIC16/17 microcontrollers employ an advanced RISC architecture. The PIC16CXX microcontroller family has enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with separate 8-bit wide data. The two stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches (which require two cycles). A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16CXX microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The **PIC16C61** device has 36 bytes of RAM and 13 I/O pins. In addition a timer/counter is available.

The **PIC16C62/62A/R62** devices have 128 bytes of RAM and 22 I/O pins. In addition, several peripheral features are available, including: three timer/counters, one Capture/Compare/PWM module and one serial port. The Synchronous Serial Port can be configured as either a 3-wire Serial Peripheral Interface (SPITM) or the two-wire Inter-Integrated Circuit (I²C) bus.

The **PIC16C63/R63** devices have 192 bytes of RAM, while the **PIC16C66** has 368 bytes. All three devices have 22 I/O pins. In addition, several peripheral features are available, including: three timer/counters, two Capture/Compare/PWM modules and two serial ports. The Synchronous Serial Port can be configured as either a 3-wire Serial Peripheral Interface (SPI) or the two-wire Inter-Integrated Circuit (I^2C) bus. The Universal Synchronous Asynchronous Receiver Transmitter (USART) is also know as a Serial Communications Interface or SCI.

The **PIC16C64/64A/R64** devices have 128 bytes of RAM and 33 I/O pins. In addition, several peripheral features are available, including: three timer/counters, one Capture/Compare/PWM module and one serial port. The Synchronous Serial Port can be configured as either a 3-wire Serial Peripheral Interface (SPI) or the two-wire Inter-Integrated Circuit (I²C) bus. An 8-bit Parallel Slave Port is also provided.

The **PIC16C65/65A/R65** devices have 192 bytes of RAM, while the **PIC16C67** has 368 bytes. All four devices have 33 I/O pins. In addition, several peripheral features are available, including: three timer/counters, two Capture/Compare/PWM modules and two serial ports. The Synchronous Serial Port can be configured as either a 3-wire Serial Peripheral Interface (SPI) or the two-wire Inter-Integrated Circuit (I²C) bus. The Universal Synchronous Asynchronous Receiver Transmit-

ter (USART) is also known as a Serial Communications Interface or SCI. An 8-bit Parallel Slave Port is also provided.

The PIC16C6X device family has special features to reduce external components, thus reducing cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low-cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (power-down) mode offers a power saving mode. The user can wake the chip from SLEEP through several external and internal interrupts, and resets.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lockup.

A UV erasable CERDIP packaged version is ideal for code development, while the cost-effective One-Time-Programmable (OTP) version is suitable for production in any volume.

The PIC16C6X family fits perfectly in applications ranging from high-speed automotive and appliance control to low-power remote sensors, keyboards and telecom processors. The EPROM technology makes customization of application programs (transmitter codes, motor speeds, receiver frequencies, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low-cost, low-power, high performance, ease-of-use, and I/O flexibility make the PIC16C6X very versatile even in areas where no microcontroller use has been considered before (e.g. timer functions, serial communication, capture and compare, PWM functions, and co-processor applications).

1.1 Family and Upward Compatibility

Those users familiar with the PIC16C5X family of microcontrollers will realize that this is an enhanced version of the PIC16C5X architecture. Please refer to Appendix A for a detailed list of enhancements. Code written for PIC16C5X can be easily ported to PIC16CXX family of devices (Appendix B).

1.2 Development Support

PIC16C6X devices are supported by the complete line of Microchip Development tools.

Please refer to Section 15.0 for more details about Microchip's development tools.

4.0 MEMORY ORGANIZATION

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

4.1 Program Memory Organization

The PIC16C6X family has a 13-bit program counter capable of addressing an $8K \times 14$ program memory space. The amount of program memory available to each device is listed below:

Device	Program Memory	Address Range
PIC16C61	1K x 14	0000h-03FFh
PIC16C62	2K x 14	0000h-07FFh
PIC16C62A	2K x 14	0000h-07FFh
PIC16CR62	2K x 14	0000h-07FFh
PIC16C63	4K x 14	0000h-0FFFh
PIC16CR63	4K x 14	0000h-0FFFh
PIC16C64	2K x 14	0000h-07FFh
PIC16C64A	2K x 14	0000h-07FFh
PIC16CR64	2K x 14	0000h-07FFh
PIC16C65	4K x 14	0000h-0FFFh
PIC16C65A	4K x 14	0000h-0FFFh
PIC16CR65	4K x 14	0000h-0FFFh
PIC16C66	8K x 14	0000h-1FFFh
PIC16C67	8K x 14	0000h-1FFFh

For those devices with less than 8K program memory, accessing a location above the physically implemented address will cause a wraparound.

The reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 4-1: PIC16C61 PROGRAM MEMORY MAP AND STACK

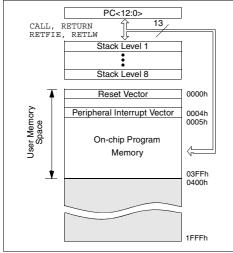


FIGURE 4-2: PIC16C62/62A/R62/64/64A/ R64 PROGRAM MEMORY MAP AND STACK

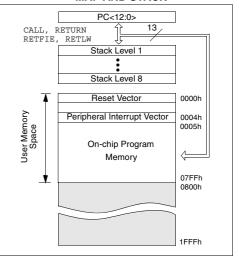
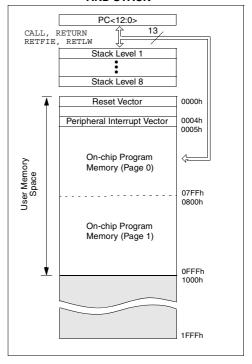


FIGURE 4-3: PIC16C63/R63/65/65A/R65 PROGRAM MEMORY MAP AND STACK



Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets ⁽³⁾
Bank 0											·
00h ⁽¹⁾	INDF	Addressing	this location	uses conter	ts of FSR to	address data	a memory (n	ot a physica	register)	0000 0000	0000 0000
01h	TMR0	Timer0 mod	lule's registe	r						xxxx xxxx	uuuu uuuu
02h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Signif	icant Byte					0000 0000	0000 0000
03h ⁽¹⁾	STATUS	IRP ⁽⁵⁾	RP1 ⁽⁵⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
04h ⁽¹⁾	FSR	Indirect data	a memory ad	dress pointe	r					xxxx xxxx	uuuu uuuu
05h	PORTA	-	_	PORTA Dat	a Latch wher	n written: PO	RTA pins wh	en read		xx xxxx	uu uuuu
06h	PORTB	PORTB Dat	ta Latch whe	n written: PC	ORTB pins wi	nen read				xxxx xxxx	uuuu uuuu
07h	PORTC	PORTC Da	ta Latch whe	n written: PC	ORTC pins w	hen read				xxxx xxxx	uuuu uuuu
08h	PORTD	PORTD Dat	ta Latch whe	n written: PC	ORTD pins w	hen read				xxxx xxxx	uuuu uuuu
09h	PORTE		—	_	_	—	RE2	RE1	RE0	xxx	uuu
0Ah ^(1,2)	PCLATH		_	_	Write Buffer	for the uppe	r 5 bits of the	e Program C	ounter	0 0000	0 0000
0Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF	(6)	_	1	SSPIF	CCP1IF	TMR2IF	TMR1IF	00 0000	00 0000
0Dh	_	Unimpleme	nted							—	_
0Eh	TMR1L	Holding reg	ister for the L	east Signific	ant Byte of t	he 16-bit TM	R1 register			xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding reg	ister for the M	/lost Signific	ant Byte of th	ne 16-bit TMF	R1 register			xxxx xxxx	uuuu uuuu
10h	T1CON	-	_	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	00 0000	uu uuuu
11h	TMR2	Timer2 mod	lule's registe	r						0000 0000	0000 0000
12h	T2CON		TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h	SSPBUF	Synchronou	us Serial Port	Receive Bu	ffer/Transmit	Register				xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	СКР	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
15h	CCPR1L	Capture/Compare/PWM1 (LSB)						xxxx xxxx	uuuu uuuu		
16h	CCPR1H	Capture/Compare/PWM1 (MSB)					uuuu uuuu				
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 0000
18h-1Fh	_	Unimpleme	nted							_	

TABLE 4-4: SPECIAL FUNCTION REGISTERS FOR THE PIC16C64/64A/R64

Note 1: These registers can be addressed from either bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)

3: Other (non power-up) resets include external reset through MCLR and the Watchdog Timer reset.

4: The BOR bit is reserved on the PIC16C64, always maintain this bit set.

5: The IRP and RP1 bits are reserved on the PIC16C64/64A/R64, always maintain these bits clear.

6: PIE1<6> and PIR1<6> are reserved on the PIC16C64/64A/R64, always maintain these bits clear.

9.0 TIMER2 MODULE

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Timer2 is an 8-bit timer with a prescaler and a postscaler. It is especially suitable as PWM time-base for PWM mode of CCP module(s). TMR2 is a readable and writable register, and is cleared on any device reset.

The input clock (FOSC/4) has a prescale option of 1:1, 1:4 or 1:16, selected by control bits T2CKPS1:T2CKPS0 (T2CON<1:0>).

The Timer2 module has an 8-bit period register, PR2. Timer2 increments from 00h until it matches PR2 and then resets to 00h on the next increment cycle. PR2 is a readable and writable register. The PR2 register is initialized to FFh upon reset.

The match output of the TMR2 register goes through a 4-bit postscaler (which gives a 1:1 to 1:16 scaling, inclusive) to generate a TMR2 interrupt (latched in flag bit TMR2IF (PIR1<1>)).

The Timer2 module can be shut off by clearing control bit TMR2ON (T2CON<2>) to minimize power consumption.

Figure 9-2 shows the Timer2 control register. T2CON is cleared upon reset which initializes Timer2 as shut off with the prescaler and postscaler at a 1:1 value.

9.1 Timer2 Prescaler and Postscaler

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The prescaler and postscaler counters are cleared when any of the following occurs:

- a write to the TMR2 register
- · a write to the T2CON register
- any device reset (POR, BOR, MCLR Reset, or WDT Reset).

TMR2 is not cleared when T2CON is written.

9.2 Output of TMR2

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The output of TMR2 (before the postscaler) is fed to the Synchronous Serial Port module which optionally uses it to generate shift clock.

FIGURE 9-1: TIMER2 BLOCK DIAGRAM

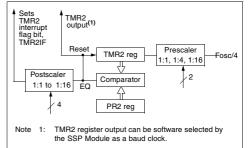


FIGURE 9-2: T2CON: TIMER2 CONTROL REGISTER (ADDRESS 12h)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
_	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	R = Readable bit
bit7 bit 7:	Unimplem	ented : Rea	ud as '0'				bit0	W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR reset
bit 6-3:		TOUTPS0: postscale postscale	Timer2 Ou	itput Postsc	ale Select bi	ts		
bit 2:	TMR2ON : 1 = Timer2 0 = Timer2	is on	bit					
bit 1-0:	T2CKPS1: 00 = 1:1 pr 01 = 1:4 pr 1x = 1:16 p	escale rescale	Timer2 Clo	ock Prescale	e Select bits			

To enable the serial port, SSP enable bit SSPEN (SSPCON<5>) must be set. To reset or reconfigure SPI mode, clear enable bit SSPEN, re-initialize SSPCON register, and then set enable bit SSPEN. This configures the SDI, SDO, SCK, and \overline{SS} pins as serial port pins. For the pins to behave as the serial port function, they must have their data direction bits (in the TRIS register) appropriately programmed. That is:

- SDI must have TRISC<4> set
- SDO must have TRISC<5> cleared
- SCK (Master mode) must have TRISC<3> cleared
- SCK (Slave mode) must have TRISC<3> set
- SS must have TRISA<5> set (if implemented)

Any serial port function that is not desired may be overridden by programming the corresponding data direction (TRIS) register to the opposite value. An example would be in master mode where you are only sending data (to a display driver), then both SDI and SS could be used as general purpose outputs by clearing their corresponding TRIS register bits.

Figure 11-4 shows a typical connection between two microcontrollers. The master controller (Processor 1) initiates the data transfer by sending the SCK signal. Data is shifted out of both shift registers on their programmed clock edge, and latched on the opposite edge of the clock. Both processors should be programmed to the same Clock Polarity (CKP), then both controllers would send and receive data at the same time. Whether the data is meaningful (or dummy data) depends on the application software. This leads to three scenarios for data transmission:

- Master sends data Slave sends dummy data
- Master sends data Slave sends data
- · Master sends dummy data Slave sends data

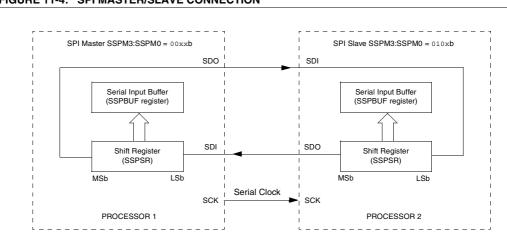


FIGURE 11-4: SPI MASTER/SLAVE CONNECTION

The master can initiate the data transfer at any time because it controls the SCK. The master determines when the slave (Processor 2) is to broadcast data by the software protocol.

In master mode the data is transmitted/received as soon as the SSPBUF register is written to. If the SPI is only going to receive, the SCK output could be disabled (programmed as an input). The SSPSR register will continue to shift in the signal present on the SDI pin at the programmed clock rate. As each byte is received, it will be loaded into the SSPBUF register as if a normal received byte (interrupts and status bits appropriately set). This could be useful in receiver applications as a "line activity monitor" mode.

In slave mode, the data is transmitted and received as the external clock pulses appear on SCK. When the last bit is latched interrupt flag bit SSPIF (PIR1<3>) is set.

The clock polarity is selected by appropriately programming bit CKP (SSPCON<4>). This then would give waveforms for SPI communication as shown in Figure 11-5 and Figure 11-6 where the MSB is transmitted first. In master mode, the SPI clock rate (bit rate) is user programmable to be one of the following:

- Fosc/4 (or TCY)
- Fosc/16 (or 4 TCY)
- Fosc/64 (or 16 TCY)
- Timer2 output/2

This allows a maximum bit clock frequency (at 20 MHz) of 5 MHz. When in slave mode the external clock must meet the minimum high and low times.

In sleep mode, the slave can transmit and receive data and wake the device from sleep.

Γ

FIGURE 11-8: SSPCON: SYNC SERIAL PORT CONTROL REGISTER (ADDRESS 14h)(PIC16C66/67)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	R = Readable bit W = Writable bit
oit7							bit0	U = Unimplemented bit, rea as '0' - n =Value at POR reset
bit 7:	WCOL: W 1 = The SS (must be c 0 = No col	SPBUF reg	gister is wi		e it is still ti	ransmitting	g the previo	us word
bit 6:	SSPOV: R	eceive Ov	erflow Indi	cator bit				
	the data in if only tran	byte is rece SSPSR is smitting da tion (and t	lost. Over ata, to avo	flow can c bid setting	only occur overflow.	in slave m n master	ode. The us	revious data. In case of overflo er must read the SSPBUF, eve verflow bit is not set since eac egister.
	$\frac{\ln l^2 C \mod}{1 = A \text{ byte}}$ in transmit 0 = No over	is received mode. SS						us byte. SSPOV is a "don't car
oit 5:	SSPEN: S	ynchronou	is Serial P	ort Enable	bit			
		es serial po					is serial por t pins	t pins
	 0 = Disables serial port and configures these pins as I/O port pins <u>In I²C mode</u> 1 = Enables the serial port and configures the SDA and SCL pins as serial port pins 0 = Disables serial port and configures these pins as I/O port pins In both modes, when enabled, these pins must be properly configured as input or output. 							
bit 4:	CKP : Cloc In SPI mod 1 = Idle sta 0 = Idle sta In I^2C mod SCK relea 1 = Enable 0 = Holds	<u>de</u> ate for cloc ate for cloc <u>de</u> se control e clock	k is a high k is a low	level	to ensure	data setu	p time)	
bit 3-0:	$0110 = ^{2}(0)$ $0111 = ^{2}(0)$ $1011 = ^{2}(0)$ $1110 = ^{2}(0)$	PI master r PI master r PI master r PI master r PI slave mo CI slave mo CI slave mo CI slave mo CI slave mo	node, cloc node, cloc node, cloc ode, clock ode, clock ode, clock de, 7-bit a de, 10-bit controllec de, 7-bit a	k = Fosc/. k = Fosc/. k = Fosc/. k = TMR2 = SCK pir address address I master m address wi	4 64 output/2 a. <u>SS</u> pin c a. <u>SS</u> pin c node (slave th start an	ontrol ena ontrol disa e idle) d stop bit		

13.8 Power-down Mode (SLEEP)

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, status bit \overline{PD} (STATUS<3>) is cleared, status bit \overline{TO} (STATUS<4>) is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either VDD, or VSS, ensure no external circuitry is drawing current from the I/O pin, and disable external clocks. Pull all I/O pins, that are hi-impedance inputs, high or low externally to avoid switching currents caused by floating inputs. The TOCKI input should also be at VDD or VSS for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{\text{MCLR}}/\text{VPP}$ pin must be at a logic high level (VIHMC).

13.8.1 WAKE-UP FROM SLEEP

The device can wake from SLEEP through one of the following events:

- 1. External reset input on MCLR/VPP pin.
- 2. Watchdog Timer Wake-up (if WDT was enabled).
- 3. Interrupt from RB0/INT pin, RB port change, or some peripheral interrupts.

External $\overline{\text{MCLR}}$ Reset will cause a device reset. All other events are considered a continuation of program execution and cause a "wake-up". The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits in the STATUS register can be used to determine the cause of device reset. The $\overline{\text{PD}}$ bit, which is set on power-up is cleared when SLEEP is invoked. The $\overline{\text{TO}}$ bit is cleared if WDT time-out occurred (and caused wake-up).

The following peripheral interrupts can wake the device from SLEEP:

- 1. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
- 2. SSP (Start/Stop) bit detect interrupt.
- 3. SSP transmit or receive in slave mode (SPI/I²C).
- 4. CCP capture mode interrupt.
- 5. Parallel Slave Port read or write.
- 6. USART TX or RX (synchronous slave mode).

Other peripherals can not generate interrupts since during SLEEP, no on-chip Q clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction after the subset of the new provide the instruction after the subset (on address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

13.8.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs before the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the TO bit will not be set and PD bits will not be cleared.
- If the interrupt occurs during or after the execution of a SLEEP instruction, the device will immediately wake up from sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the TO bit will be set and the PD bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the \overline{PD} bit. If the \overline{PD} bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

Instruction Descriptions 14.1

Add Lite	ral and	w	
[<i>label</i>] ADDLW k			
$0 \le k \le 255$			
(W) + k –	→ (W)		
C, DC, Z			
11	111x	kkkk	kkkk
The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.			
1			
1			
Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W
After Inst	W = ruction	0x10 0x25	
	[<i>label</i>] Al $0 \le k \le 2\xi$ (W) + k - C, DC, Z 11 The conte added to the result is pl 1 1 Q1 Decode ADDLW Before In After Inst	$ \begin{array}{l lllllllllllllllllllllllllllllllllll$	$0 \le k \le 255$ (W) + k → (W) C, DC, Z $11 111x kkkk$ The contents of the W register added to the eight bit literal 'k' result is placed in the W regist 1 1 2 2 2 2 2 3 2 2 2 3 2 2 3 2 3 2 3 3 2 3

ANDLW	AND Lite	eral with	W		
Syntax:	[<i>label</i>] A	[<i>label</i>] ANDLW k			
Operands:	$0 \le k \le 25$	55			
Operation:	(W) .AND	D. (k) \rightarrow (W)		
Status Affected:	Z				
Encoding:	11	1001	kkkk	kkkk	
Description:	The conter AND'ed wird result is pl	th the eig	ht bit literal	'k'. The	
Words:	1				
Cycles:	1				
Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	Read literal "k"	Process data	Write to W	
Example	ANDLW	0x5F			
	Before In	struction			
	After Inst		0xA3		
		W =	0x03		

ADDWF	Add W and f				
Syntax:	[<i>label</i>] A	DDWF	f,d		
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$				
Operation:	(W) + (f) \rightarrow (destination)				
Status Affected:	C, DC, Z				
Encoding:	00	0111	dfff	ffff	
Description:	Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.				
Words:	1				
Cycles:	1				
Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	Read register 'f'	Process data	Write to destination	
Evennle	ADDUE	BOD	<u>.</u>		
Example	ADDWF		0		
	Before In	structior	ו 0x17		
	W = 0x17 FSR = 0xC2				
	After Inst				
		W = FSR =	0xD9 0xC2		

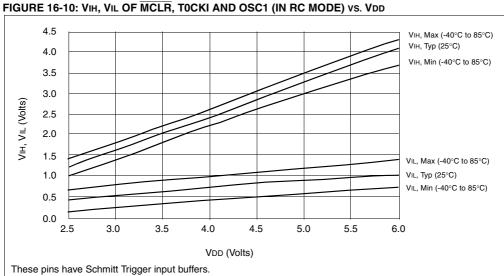
ANDWF	AND W v	vith f		
Syntax:	[<i>label</i>] Al	NDWF	f,d	
Operands:	$\begin{array}{l} 0 \leq f \leq 12 \\ d \in [0,1] \end{array}$	7		
Operation:	(W) .AND	0. (f) \rightarrow (e	destinatio	on)
Status Affected:	Z			
Encoding:	0.0	0101	dfff	ffff
Description:	AND the W is 0 the res ter. If 'd' is register 'f'.	sult is stor 1 the res	red in the	W regis-
Words:	1			
Cycles:	1			
Q Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	Read register 'f'	Process data	Write to destination
Example	ANDWF	FSR,	1	
	Before In			
		W = FSR =	0x17 0xC2	
	After Inst		0102	
		W =	0x17	
		FSR =	0x02	

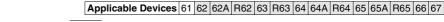
NOP	No Operation				
Syntax:	[label]	NOP			
Operands:	None				
Operation:	No opera	ition			
Status Affected:	None				
Encoding:	00	0000	0xx0	0000	
Description:	No operat	ion.			
Words:	1				
Cycles:	1				
Q Cycle Activity:	Q1	Q2	Q3	Q4	
	Decode	No- Operation	No- Operation	No- Operation	
Example	NOP				

RETFIE	Return from Interrupt				
Syntax:	[label]	RETFIE			
Operands:	None				
Operation:	$\begin{array}{l} TOS \to PC, \\ 1 \to GIE \end{array}$				
Status Affected:	None				
Encoding:	00	0000	0000	1001	
	PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two cycle instruction.				
	Global Inte (INTCON<	, errupt Ena <7>). This	ble bit, ĠIE	Ē	
Words:	Global Inte (INTCON<	, errupt Ena <7>). This	ble bit, ĠIE	Ē	
Words: Cycles:	Global Inte (INTCON< instruction	, errupt Ena <7>). This	ble bit, ĠIE	Ē	
	Global Inte (INTCON< instruction	, errupt Ena <7>). This	ble bit, ĠIE	Ē	
Cycles:	Global Inte (INTCON< instruction 1 2	errupt Ena (7>). This	ble bit, GIE is a two cy	E cle	
Cycles: Q Cycle Activity:	Global Inte (INTCON- instruction 1 2 Q1	Q2 No-	ble bit, GIE is a two cy Q3 Set the	cle Q4 Pop from	

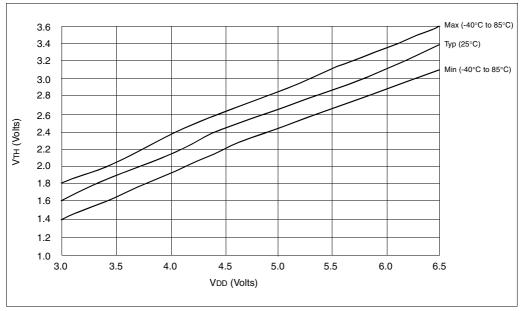
After Interrupt PC = TOS GIE = 1

OPTION	Load Option Register			
Syntax:	[label] OPTION			
Operands:	None			
Operation:	$(W) \rightarrow OPTION$			
Status Affected:	None			
Encoding:	00 0000 0110 0010			
Description: Words: Cycles:	The contents of the W register are loaded in the OPTION register. This instruction is supported for code com- patibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it. 1			
Example	To maintain upward compatibility with future PIC16CXX products, do not use this instruction.			









Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 17-10: I²C BUS DATA TIMING

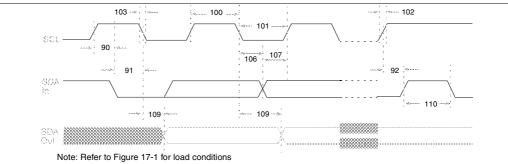


TABLE 17-10: I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100	Тнідн	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	0.6	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY	—		
101	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5Tcy			
102	TR	SDA and SCL rise	100 kHz mode	—	1000	ns	
		time	400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
103	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
90	TSU:STA	START condition	100 kHz mode	4.7	—	μs	Only relevant for repeated
		setup time	400 kHz mode	0.6		μs	START condition
91	THD:STA	START condition hold	100 kHz mode	4.0	_	μs	After this period the first clock
		time	400 kHz mode	0.6	—	μs	pulse is generated
106	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92	TSU:STO	STOP condition setup	100 kHz mode	4.7	—	μs	
		time	400 kHz mode	0.6	—	μs	
109	ΤΑΑ	Output valid from	100 kHz mode	—	3500	ns	Note 1
		clock	400 kHz mode	—	—	ns	
110	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free
			400 kHz mode	1.3	_	μs	before a new transmission can start
	Cb	Bus capacitive loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz) I²C-bus system, but the requirement tsu;DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max. + tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the SCL line is released.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

20.0 ELECTRICAL CHARACTERISTICS FOR PIC16C63/65A

Absolute Maximum Ratings (†)

Ambient temperature under bias	55°C to +125°C
Storage temperature	65°C to +150°C
Voltage on any pin with respect to Vss (except VDD, MCLR, and RA4)	0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS	0.3V to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	
Voltage on RA4 with respect to Vss	0V to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of Vss pin	
Maximum current into VDD pin	250 mA
Input clamp current, Iк (VI < 0 or VI > VDD)	±20 mA
Output clamp current, loк (Vo < 0 or Vo > VDD)	±20 mA
Maximum output current sunk by any I/O pin	
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (Note 3) (combined)	200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (Note 3) (combined)	200 mA
Maximum current sunk by PORTC and PORTD (Note 3) (combined)	200 mA
Maximum current sourced by PORTC and PORTD (Note 3) (combined)	200 mA
Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - \sum IOH} + \sum {(VDD-V	′он) x Iон} + ∑(Vol x Iol)

- Note 2: Voltage spikes below Vss at the MCLR/VPP pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the MCLR/VPP pin rather than pulling this pin directly to Vss.
- Note 3: PORTD and PORTE not available on the PIC16C63.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 20-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

osc	PIC16C63-04 PIC16C65A-04	PIC16C63-10 PIC16C65A-10	PIC16C63-20 PIC16C65A-20	PIC16LC63-04 PIC16LC65A-04	JW Devices	
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.	
XT	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 µA max. at 4V Freq: 4 MHz max.	
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V		VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V	
	IPD: 1.5 μA typ. at 4.5V Freq: 4 MHz max.	IPD 1.5 μA typ. at 4.5V Freq: 10 MHz max.	IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.		IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.	
LP	VDD: 4.0V to 6.0V IDD: 52.5 μA typ. at 32 kHz, 4.0V IPD: 0.9 μA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.	VDD: 2.5V to 6.0V IDD: 48 μA max. at 32 kHz, 3.0V IPD: 5 μA max. at 3.0V Freq: 200 kHz max.	

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

20.2 DC Characteristics: PIC16LC63/65A-04 (Commercial, Industrial)

DC CHA		Standaı Operatir		•		°C ≤	Inless otherwise stated) TA \leq +85°C for industrial and TA \leq +70°C for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001	Supply Voltage	Vdd	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020	Power-down Current	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021	(Note 3, 5)		-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C
D023*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

- $\overline{MCLR} = VDD$; WDT enabled/disabled as specified.
- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.
- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
- 5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.
- 6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

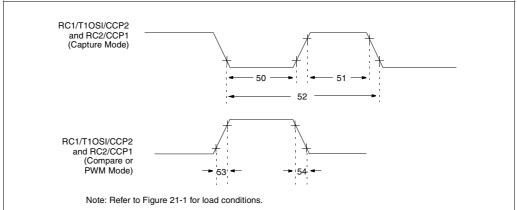


FIGURE 21-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)

TABLE 21-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

Param No.	Sym	Characteristic			Min	Тур†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2	No Prescaler		0.5TCY + 20	—	_	ns	
		input low time	With Prescaler	PIC16CR63/R65	10	—	—	ns	
				PIC16LCR63/R65	20	-	_	ns	
51*	51* TccH CCP1 and CCP2		No Prescaler		0.5TCY + 20	—	—	ns	
		input high time	With Prescaler	PIC16CR63/R65	10	_	_	ns	
				PIC16LCR63/R65	20	-	_	ns	
52*	TccP	CCP1 and CCP2 ir	CP1 and CCP2 input period		<u>3Tcy + 40</u> N	-	—	ns	N = prescale value (1,4, or 16)
53*	TccR	CCP1 and CCP2 o	utput rise time	PIC16CR63/R65	_	10	25	ns	
				PIC16LCR63/R65	_	25	45	ns	
54*	54* TccF CCP1 and CCP2 output fall time		utput fall time	PIC16 CR 63/R65	—	10	25	ns	
				PIC16LCR63/R65	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 21-8: PARALLEL SLAVE PORT TIMING (PIC16CR65)

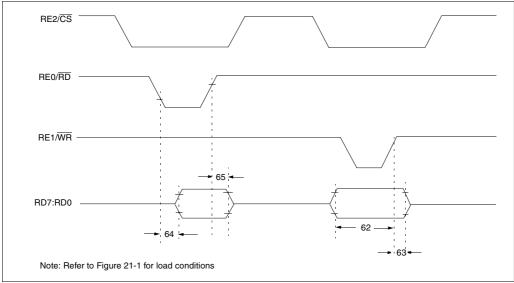


TABLE 21-7: PARALLEL SLAVE PORT REQUIREMENTS (PIC16CR65)

Sym	Characteristic		Min	Тур†	Max	Units	Conditions
TdtV2wrH	Data in valid before \overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} (setup time)		20	_	_	ns	
		PIC16 CR 65	20	_	—	ns	
	time)	PIC16 LCR 65	35	—	—	ns	
TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data–out valid		-	—	80	ns	
TrdH2dtl	RD↑ or CS↑ to data–out invalid		10	—	30	ns	
	TdtV2wrH TwrH2dtl TrdL2dtV	TdtV2wrH Data in valid before WR↑ or CS↑ (setu TwrH2dtl WR↑ or CS↑ to data–in invalid (hold time) TrdL2dtV RD↓ and CS↓ to data–out valid	TdtV2wrH Data in valid before WR↑ or CS↑ (setup time) TwrH2dtl WR↑ or CS↑ to data-in invalid (hold time) PIC16CR65 PIC16LCR65 TrdL2dtV RD↓ and CS↓ to data-out valid	TdtV2wrH Data in valid before WR↑ or CS↑ (setup time) 20 TwrH2dtl WR↑ or CS↑ to data-in invalid (hold time) PIC16CR65 20 TrdL2dtV RD↓ and CS↓ to data-out valid	TdtV2wrH Data in valid before \overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} (setup time) 20 TwrH2dtl \overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} to data-in invalid (hold time) PIC16 CR 65 20 TrdL2dtV $\overline{RD}^{\downarrow}$ and $\overline{CS}^{\downarrow}$ to data-out valid	TdtV2wrH Data in valid before \overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} (seture time) 20 TwrH2dtl \overline{WR}^{\uparrow} or \overline{CS}^{\uparrow} to data-in invalid (hold time) PIC16 CR 65 20 TrdL2dtV $\overline{RD}_{\downarrow}$ and $\overline{CS}_{\downarrow}$ to data-out valid 80	TdtV2wrH Data in valid before \overline{WR} or \overline{CS} (setup time) 20 ns TwrH2dtl \overline{WR} or \overline{CS} to data-in invalid (hold time) PIC16 CR 65 20 ns TrdL2dtV \overline{RD} and \overline{CS} to data-out valid ns ns TrdL2dtV \overline{RD} and \overline{CS} to data-out valid ns

These parameters are characterized but not tested.

t Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 22-3: CLKOUT AND I/O TIMING

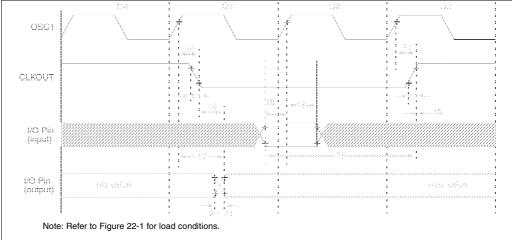


TABLE 22-3:	CLKOUT AND I/O TIMING REQUIREMENTS

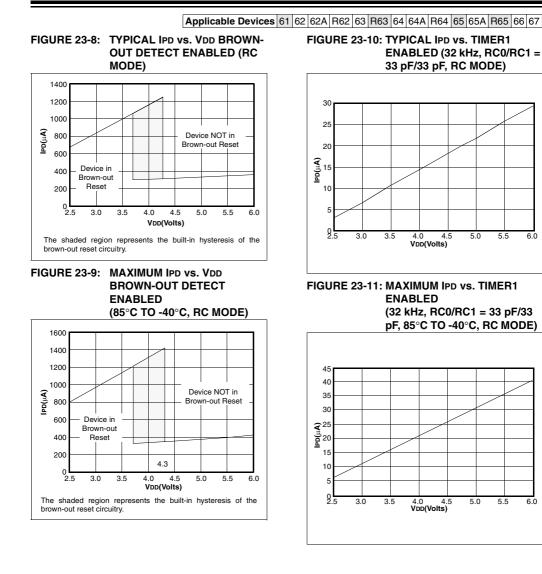
Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		-	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑		—	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		_	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		_	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid		_	_	0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑		Tosc + 200	_	-	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT ↑		0	_	_	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		_	50	150	ns	
18*	TosH2iol	OSC1↑ (Q2 cycle) to Port input	PIC16 C 66/67	100	_	_	ns	
		invalid (I/O in hold time)	PIC16LC66/67	200	_	_	ns	
19*	TioV2osH	Port input valid to OSC1 [↑] (I/O in	setup time)	0	_	_	ns	
20*	TioR	Port output rise time	PIC16 C 66/67	_	10	40	ns	
			PIC16LC66/67	_	_	80	ns	
21*	TioF	Port output fall time	PIC16 C 66/67	-	10	40	ns	
			PIC16LC66/67	_	_	80	ns	
22††*	Tinp	INT pin high or low time		Тсү	_	_	ns	
23††*	Trbp	RB7:RB4 change INT high or low	/ time	Тсү	—	_	ns	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

tt These parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.



Data based on matrix samples. See first page of this section for details.

PIN COMPATIBILITY

Devices that have the same package type and VDD, VSs and $\overline{\text{MCLR}}$ pin locations are said to be pin compatible. This allows these different devices to operate in the same socket. Compatible devices may only requires minor software modification to allow proper operation in the application socket (ex., PIC16C56 and PIC16C61 devices). Not all devices in the same package size are pin compatible; for example, the PIC16C62 is compatible with the PIC16C63, but not the PIC16C55.

Pin compatibility does not mean that the devices offer the same features. As an example, the PIC16C54 is pin compatible with the PIC16C71, but does not have an A/D converter, weak pull-ups on PORTB, or interrupts.

Pin Compatible Devices	Package
PIC12C508, PIC12C509, PIC12C671, PIC12C672	8-pin
PIC16C154, PIC16CR154, PIC16C156, PIC16CR156, PIC16C158, PIC16CR158, PIC16C52, PIC16C54, PIC16C54A, PIC16C56, PIC16C58A, PIC16CR58A, PIC16C554, PIC16CR58A, PIC16C554, PIC16C556, PIC16C558 PIC16C620, PIC16C621, PIC16C622 PIC16C641, PIC16C642, PIC16C661, PIC16C662 PIC16C710, PIC16C71, PIC16C711, PIC16C715 PIC16F83, PIC16CR83, PIC16F84A, PIC16CR84	18-pin, 20-pin
PIC16C55, PIC16C57, PIC16CR57B	28-pin
PIC16CR62, PIC16C62A, PIC16C63, PIC16CR63, PIC16C66, PIC16C72, PIC16C73A, PIC16C76	28-pin
PIC16CR64, PIC16C64A, PIC16C65A, PIC16CR65, PIC16C67, PIC16C74A, PIC16C77	40-pin
PIC17CR42, PIC17C42A, PIC17C43, PIC17CR43, PIC17C44	40-pin
PIC16C923, PIC16C924	64/68-pin
PIC17C756, PIC17C752	64/68-pin

TABLE F-1: PIN COMPATIBLE DEVICES

LIST OF EQUATION AND EXAMPLES

Example 3-1:	Instruction Pipeline Flow 18
Example 4-1:	Call of a Subroutine in Page 1
	from Page 0 49
Example 4-2:	Indirect Addressing 49
Example 5-1:	Initializing PORTA51
Example 5-2:	Initializing PORTB53
Example 5-3:	Initializing PORTC55
Example 5-4:	Read-Modify-Write Instructions on an
	I/O Port 60
Example 7-1:	Changing Prescaler (Timer0→WDT)69
Example 7-2:	Changing Prescaler (WDT→Timer0)69
Example 8-1:	Reading a 16-bit
	Free-running Timer73
Example 10-1:	Changing Between
	Capture Prescalers79
Example 10-2:	PWM Period and Duty
	Cycle Calculation81
Example 11-1:	Loading the SSPBUF
	(SSPSR) Register
Example 11-2:	Loading the SSPBUF
	(SSPSR) Register (PIC16C66/67)91
Example 12-1:	Calculating Baud Rate Error 107
Example 13-1:	Saving Status and W
	Registers in RAM139
Example 13-2:	Saving Status, W, and
	PCLATH Registers in RAM
	(All other PIC16C6X devices)

LIST OF FIGURES

Figure 3-1:	PIC16C61 Block Diagram10
Figure 3-2:	PIC16C62/62A/R62/64/64A/R64
	Block Diagram11
Figure 3-3:	PIC16C63/R63/65/65A/R65
	Block Diagram12
Figure 3-4:	PIC16C66/67 Block Diagram 13
Figure 3-5:	Clock/Instruction Cycle18
Figure 4-1:	PIC16C61 Program Memory Map
	and Stack19
Figure 4-2:	PIC16C62/62A/R62/64/64A/
	R64 Program Memory Map and Stack 19
Figure 4-3:	PIC16C63/R63/65/65A/R65 Program
	Memory Map and Stack19
Figure 4-4:	PIC16C66/67 Program Memory
	Map and Stack
Figure 4-5:	PIC16C61 Register File Map20
Figure 4-6:	PIC16C62/62A/R62/64/64A/
	R64 Register File Map21
Figure 4-7:	PIC16C63/R63/65/65A/R65
	Register File Map21
Figure 4-8:	PIC16C66/67 Data Memory Map22
Figure 4-9:	STATUS Register
	(Address 03h, 83h, 103h, 183h)35
Figure 4-10:	OPTION Register
	(Address 81h, 181h)36
Figure 4-11:	INTCON Register
	(Address 0Bh, 8Bh, 10Bh 18Bh)37
Figure 4-12:	PIE1 Register for PIC16C62/62A/R62
	(Address 8Ch)
Figure 4-13:	PIE1 Register for PIC16C63/R63/66
	(Address 8Ch)39
Figure 4-14:	PIE1 Register for PIC16C64/64A/R64
	(Address 8Ch)

Figure 4-15:	PIE1 Register for PIC16C65/65A/R65/67
	(Address 8Ch) 40
Figure 4-16:	PIR1 Register for PIC16C62/62A/R62
	(Address 0Ch) 41
Figure 4-17:	PIR1 Register for PIC16C63/R63/66
Eiseren 4 10	Address 0Ch)
Figure 4-18:	PIR1 Register for PIC16C64/64A/R64
Eiguro 4 10:	(Address 0Ch)
Figure 4-19:	PIR1 Register for PIC16C65/65A/R65/67 (Address 0Ch)
Figure 4-20:	PIE2 Register (Address 8Dh)
Figure 4-21:	PIR2 Register (Address 0Dh)
Figure 4-22:	PCON Register for PIC16C62/64/65
5.	(Address 8Eh) 47
Figure 4-23:	PCON Register for PIC16C62A/R62/63/
-	R63/64A/R64/65A/R65/66/67
	(Address 8Eh) 47
Figure 4-24:	Loading of PC in Different Situations 48
Figure 4-25:	Direct/Indirect Addressing 49
Figure 5-1:	Block Diagram of the
	RA3:RA0 Pins and the RA5 Pin 51
Figure 5-2:	Block Diagram of the RA4/T0CKI Pin 51
Figure 5-3:	Block Diagram of the
	RB7:RB4 Pins for PIC16C61/62/64/65 53
Figure 5-4:	Block Diagram of the
	RB7:RB4 Pins for PIC16C62A/63/R63/
	64A/65A/R65/66/67
Figure 5-5:	Block Diagram of the
Figure F C	RB3:RB0 Pins
Figure 5-6: Figure 5-7:	PORTC Block Diagram
Figure 5-7.	PORTD Block Diagram (In I/O Port Mode)57
Figure 5-8:	PORTE Block Diagram
rigure 5 0.	(In I/O Port Mode)
Figure 5-9:	TRISE Register (Address 89h)
Figure 5-10:	Successive I/O Operation
Figure 5-11:	PORTD and PORTE as a Parallel
5	Slave Port61
Figure 5-12:	Parallel Slave Port Write Waveforms 62
Figure 5-13:	Parallel Slave Port Read Waveforms 62
Figure 7-1:	Timer0 Block Diagram 65
Figure 7-2:	Timer0 Timing: Internal Clock/No
	Prescaler 65
Figure 7-3:	Timer0 Timing: Internal
	Clock/Prescale 1:2
Figure 7-4:	TMR0 Interrupt Timing
Figure 7-5:	Timer0 Timing With External Clock
Figure 7-6:	Block Diagram of the Timer0/WDT
	Prescaler
Figure 8-1:	T1CON: Timer1 Control Register
	(Address 10h)
Figure 8-2:	Timer1 Block Diagram
Figure 9-1:	T2CON: Timer2 Control Register
Figure 9-2:	(Address 12h)
Figure 10-1:	CCP1CON Register (Address 17h) /
riguio ro r.	CCP2CON Register (Address 1Dh)
Figure 10-2:	Capture Mode Operation
	Block Diagram
Figure 10-3:	Compare Mode Operation
0	Block Diagram
Figure 10-4:	Simplified PWM Block Diagram
Figure 10-5:	PWM Output 80
Figure 11-1:	SSPSTAT: Sync Serial Port Status
	Register (Address 94h) 84

Figure 11-2:	SSPCON: Sync Serial Port
	Control Register (Address 14h) 85
Figure 11-3:	SSP Block Diagram (SPI Mode) 86
Figure 11-4:	SPI Master/Slave Connection 87
Figure 11-5:	SPI Mode Timing, Master Mode or
	Slave Mode w/o SS Control
Figure 11-6:	SPI Mode Timing, Slave Mode with
	SS Control
Figure 11-7:	SSPSTAT: Sync Serial Port Status
	Register (Address 94h)(PIC16C66/67) 89
Figure 11-8:	SSPCON: Sync Serial Port Control
Figure 11 Or	Register (Address 14h)(PIC16C66/67) 90
Figure 11-9:	SSP Block Diagram (SPI Mode)
Figure 11-10:	(PIC16C66/67)91 SPI Master/Slave Connection
Figure 11-10.	(PIC16C66/67)
Figure 11-11:	SPI Mode Timing, Master Mode
rigule 11-11.	(PIC16C66/67)
Figure 11-12:	SPI Mode Timing (Slave Mode With
rigule 11-12.	CKE = 0) (PIC16C66/67)
Figure 11-13:	SPI Mode Timing (Slave Mode With
i iguio i i ioi	CKE = 1) (PIC16C66/67)
Figure 11-14:	Start and Stop Conditions
Figure 11-15:	7-bit Address Format
Figure 11-16:	I ² C 10-bit Address Format
Figure 11-17:	Slave-receiver Acknowledge
Figure 11-18:	Data Transfer Wait State
Figure 11-19:	Master-transmitter Sequence
Figure 11-20:	Master-receiver Sequence97
Figure 11-21:	Combined Format
Figure 11-22:	Multi-master Arbitration
	(Two Masters)98
Figure 11-23:	Clock Synchronization
Figure 11-24:	SSP Block Diagram (I ² C Mode)
Figure 11-25:	I ² C Waveforms for Reception
	(7-bit Address) 101
Figure 11-26:	I ² C Waveforms for Transmission
	(7-bit Address)
Figure 11-27:	Operation of the I ² C Module in
	IDLE_MODE, RCV_MODE or
Figure 10.1	XMIT_MODE
Figure 12-1:	Control Register (Address 98h) 105
Figure 12-2:	RCSTA: Receive Status and
rigule 12-2.	Control Register (Address 18h)
Figure 12-3:	RX Pin Sampling Scheme (BRGH = 0)
. iguio 12 01	PIC16C63/R63/65/65A/R65)
Figure 12-4:	RX Pin Sampling Scheme (BRGH = 1)
.g	(PIC16C63/R63/65/65A/R65) 110
Figure 12-5:	
Figure 12-5:	RX Pin Sampling Scheme (BRGH = 1)
	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65)110
Figure 12-5: Figure 12-6:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65)110 RX Pin Sampling Scheme (BRGH = 0 or = 1)
	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65)110
Figure 12-6:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65) RX Pin Sampling Scheme (BRGH = 0 or = 1) (PIC16C66/67) 111
Figure 12-6: Figure 12-7:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65) 110 RX Pin Sampling Scheme (BRGH = 0 or = 1) (PIC16C66/67) USART Transmit Block Diagram 112 Asynchronous Master Transmission Asynchronous Master Transmission
Figure 12-6: Figure 12-7: Figure 12-8: Figure 12-9:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65) 110 RX Pin Sampling Scheme (BRGH = 0 or = 1) (PIC16C66/67) USART Transmit Block Diagram 112 Asynchronous Master Transmission (Back to Back) 113
Figure 12-6: Figure 12-7: Figure 12-8:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65)
Figure 12-6: Figure 12-7: Figure 12-8: Figure 12-9: Figure 12-10: Figure 12-11:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65)
Figure 12-6: Figure 12-7: Figure 12-8: Figure 12-9: Figure 12-10: Figure 12-11: Figure 12-12:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65) 110 RX Pin Sampling Scheme (BRGH = 0 or = 1) (PIC16C66/67) USART Transmit Block Diagram 111 USART Transmit Block Diagram 113 Asynchronous Master Transmission (Back to Back) USART Receive Block Diagram 114 Asynchronous Transmission 114 Synchronous Transmission
Figure 12-6: Figure 12-7: Figure 12-8: Figure 12-9: Figure 12-10: Figure 12-11:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65) 110 RX Pin Sampling Scheme (BRGH = 0 or = 1) (PIC16C66/67) USART Transmit Block Diagram 111 USART Transmit Block Diagram 112 Asynchronous Master Transmission (Back to Back) 113 USART Receive Block Diagram 114 Asynchronous Transmission 114 Synchronous Transmission
Figure 12-6: Figure 12-7: Figure 12-8: Figure 12-9: Figure 12-10: Figure 12-11: Figure 12-12: Figure 12-13:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65)
Figure 12-6: Figure 12-7: Figure 12-8: Figure 12-9: Figure 12-10: Figure 12-11: Figure 12-12:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65) 110 RX Pin Sampling Scheme (BRGH = 0 or = 1) (PIC16C66/67) 111 USART Transmit Block Diagram 112 Asynchronous Master Transmission (Back to Back) 113 USART Receive Block Diagram 114 Asynchronous Reception 114 Synchronous Transmission 117 Synchronous Transmission 117 Synchronous Transmission 117 Synchronous Reception
Figure 12-6: Figure 12-7: Figure 12-8: Figure 12-9: Figure 12-10: Figure 12-10: Figure 12-11: Figure 12-12: Figure 12-13: Figure 12-14:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65) 110 RX Pin Sampling Scheme (BRGH = 0 or = 1) (PIC16C66/67) 111 USART Transmit Block Diagram 112 Asynchronous Master Transmission (Back to Back) USART Receive Block Diagram 114 USART Receive Block Diagram 114 Synchronous Transmission 117 Synchronous Transmission through TXEN 117 Master Mode, SREN)
Figure 12-6: Figure 12-7: Figure 12-8: Figure 12-9: Figure 12-10: Figure 12-11: Figure 12-12: Figure 12-13:	RX Pin Sampling Scheme (BRGH = 1) (PIC16C63/R63/65/65A/R65) 110 RX Pin Sampling Scheme (BRGH = 0 or = 1) (PIC16C66/67) 111 USART Transmit Block Diagram 112 Asynchronous Master Transmission (Back to Back) 113 USART Receive Block Diagram 114 Asynchronous Reception 114 Synchronous Transmission 117 Synchronous Transmission 117 Synchronous Transmission 117 Synchronous Reception

Figure 13-2:	Configuration Word for
	PIC16C62/64/65 124
Figure 13-3:	Configuration Word for
	PIC16C62A/R62/63/R63/64A/R64/
	65A/R65/66/67 124
Figure 13-4:	Crystal/Ceramic Resonator Operation
	(HS, XT or LP OSC Configuration)
Figure 13-5:	External Clock Input Operation
rigule 15-5.	(HS, XT or LP OSC Configuration)
Einung 10.0	
Figure 13-6:	External Parallel Resonant
	Crystal Oscillator Circuit 127
Figure 13-7:	External Series Resonant
	Crystal Oscillator Circuit 127
Figure 13-8:	RC Oscillator Mode 127
Figure 13-9:	Simplified Block Diagram of
	On-chip Reset Circuit 128
Figure 13-10:	Brown-out Situations 129
Figure 13-11:	Time-out Sequence on Power-up
•	(MCLR not Tied to VDD): Case 1
Figure 13-12:	Time-out Sequence on Power-up
. iguio 10 12.	(MCLR Not Tied To VDD): Case 2
Figure 13-13:	Time-out Sequence on Power-up
rigule 15-15.	(MCLR Tied to VDD)
Einung 10 14.	
Figure 13-14:	External Power-on Reset Circuit
	(For Slow VDD Power-up) 135
Figure 13-15:	External Brown-out
	Protection Circuit 1 135
Figure 13-16:	External Brown-out
	Protection Circuit 2 135
Figure 13-17:	Interrupt Logic for PIC16C61 137
Figure 13-18:	Interrupt Logic for PIC16C6X 137
Figure 13-19:	INT Pin Interrupt Timing 138
Figure 13-20:	Watchdog Timer Block Diagram 140
Figure 13-21:	Summary of Watchdog
riguie to 21.	Timer Registers 140
Figure 12.00	
Figure 13-22:	Wake-up from Sleep Through Interrupt142
Einung 10.00	
Figure 13-23:	Typical In-circuit Serial
	Programming Connection 142
Figure 14-1:	General Format for Instructions 143
Figure 16-1:	Load Conditions for Device Timing
	Specifications 168
Figure 16-2:	External Clock Timing 169
Figure 16-3:	CLKOUT and I/O Timing 170
Figure 16-4:	Reset, Watchdog Timer, Oscillator
-	Start-up Timer and Power-up Timer
	Timing 171
Figure 16-5:	Timer0 External Clock Timings 172
Figure 17-1:	Typical RC Oscillator
rigato tr ti	Frequency vs. Temperature
Eiguro 17 0	Typical RC Oscillator
Figure 17-2:	
E' 47.0	Frequency vs. VDD
Figure 17-3:	Typical RC Oscillator
	Frequency vs. VDD 174
Figure 17-4:	Typical RC Oscillator
	Frequency vs. VDD 174
Figure 17-5:	Typical IPD vs. VDD Watchdog Timer
	Disabled 25°C 174
Figure 17-6:	
	Typical IPD vs. VDD Watchdog Timer
0	Typical IPD vs. VDD Watchdog Timer Enabled 25°C 175
Ū.	Enabled 25°C 175
Figure 17-7:	Enabled 25°C 175 Maximum IPD vs. VDD Watchdog
Figure 17-7:	Enabled 25°C 175 Maximum IPD vs. VDD Watchdog Disabled
Ū.	Enabled 25°C
Figure 17-7: Figure 17-8:	Enabled 25°C
Figure 17-7:	Enabled 25°С 175 Maximum IPD vs. VDD Watchdog 175 Disabled 175 Maximum IPD vs. VDD Watchdog 175 Enabled* 176 VTH (Input Threshold Voltage) of 176
Figure 17-7: Figure 17-8:	Enabled 25°C